



## PATENT ABSTRACTS OF JAPAN

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FUKAZAWA KOICHI****(54) CHIP TYPE LIGHT EMITTING DIODE****(57) Abstract:**

**PURPOSE:** To realize a thin chip type light emitting diode while mechanical and thermal reliability necessary for a chip type light emitting diode is ensured.

**CONSTITUTION:** A pair of electrodes 23, 24 are formed on the upper surface of an insulating substrate 22. A light emitting diode element 27 is mounted on the surface of one electrode 23. The light emitting diode element 27 is wire-bonded to the surface of the other electrode 24 by using a thin metal wire 28. The light emitting diode element 27 and the thin metal wire 28 are sealed with transparent resin 29. A part of each of the backs of a pair of the electrodes 23, 24 is exposed from an insulating substrate 22. The exposed surfaces are made outer connection terminals 25, 26 of the electrodes 23, 24. Hence a thinned chip type light emitting diode as compared with prior art ones can be realized.

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